

APPLICATION SPECIFICATION

Extremport Flash Connector Receptacle, 0.6mm Pitch (G13 Series)

REVISION: A	ECR/ECN INFORMATION: EC No.: DATE: 2019/07/23	TITLE: Extremport Flash Connectors, Receptacle , 0.6mm Pitch	SHEET No. 1 of 7	
DOCUMENT NUMBER: AS-7712-001		CREATED/REVISED Sondra Sang	CHECKED BY Chenny Yeh	APPROVED BY Hank Hsu

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1.0 PURPOSE:

This specification covers the processing guidelines and the requirements for the application of Extremport Flash connector receptacle.

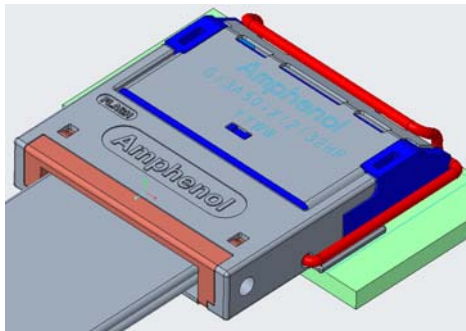
2.0 APPLICABLE DOCUMENTS AND SPECIFICATIONS:

Product Drawing
PS-7712

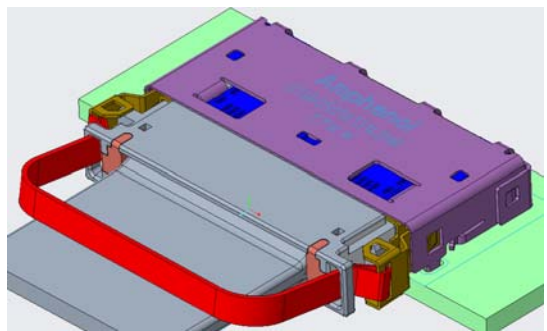
3.0 SPECIMEN:

Product are illustrated in Figure 1.

Receptacle 8X mate with Plug 8X



Flash 1.0 (with lock ring)



Flash 2.0 (with side latch)

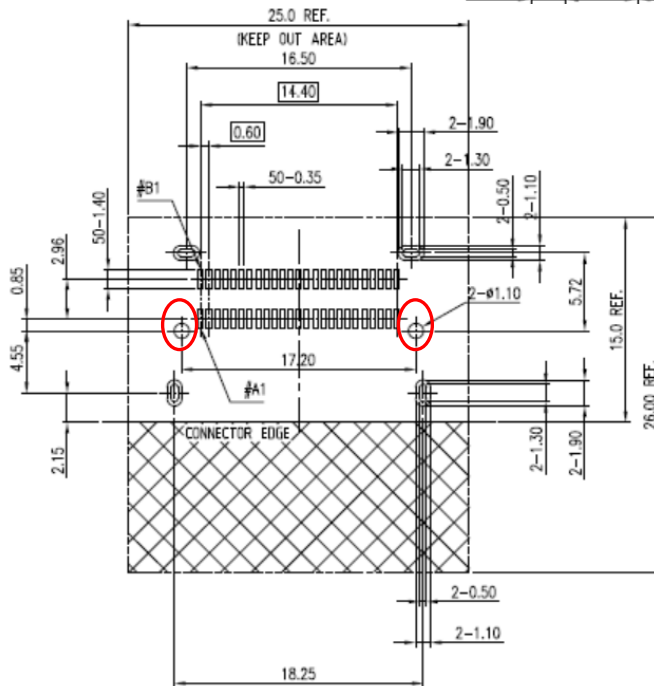
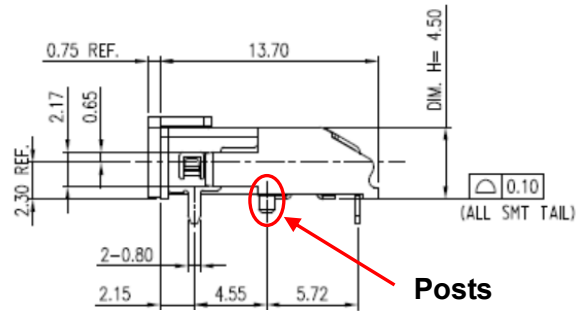
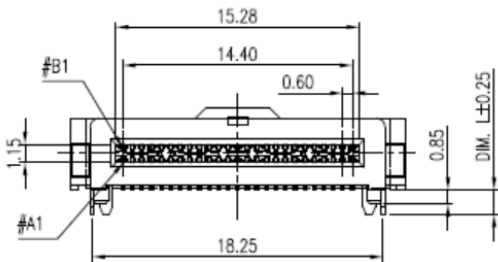
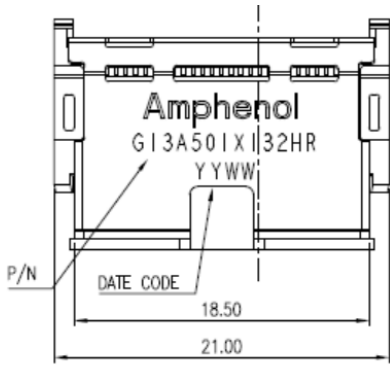
Figure 1

4.0 APPLICATION PROCESS

4.1 CONNECTOR mounts on PCB, the both side posts have to fix the PC board holes (see Figure 2) , the posts provide true position and control connector is forward on the correct direction.

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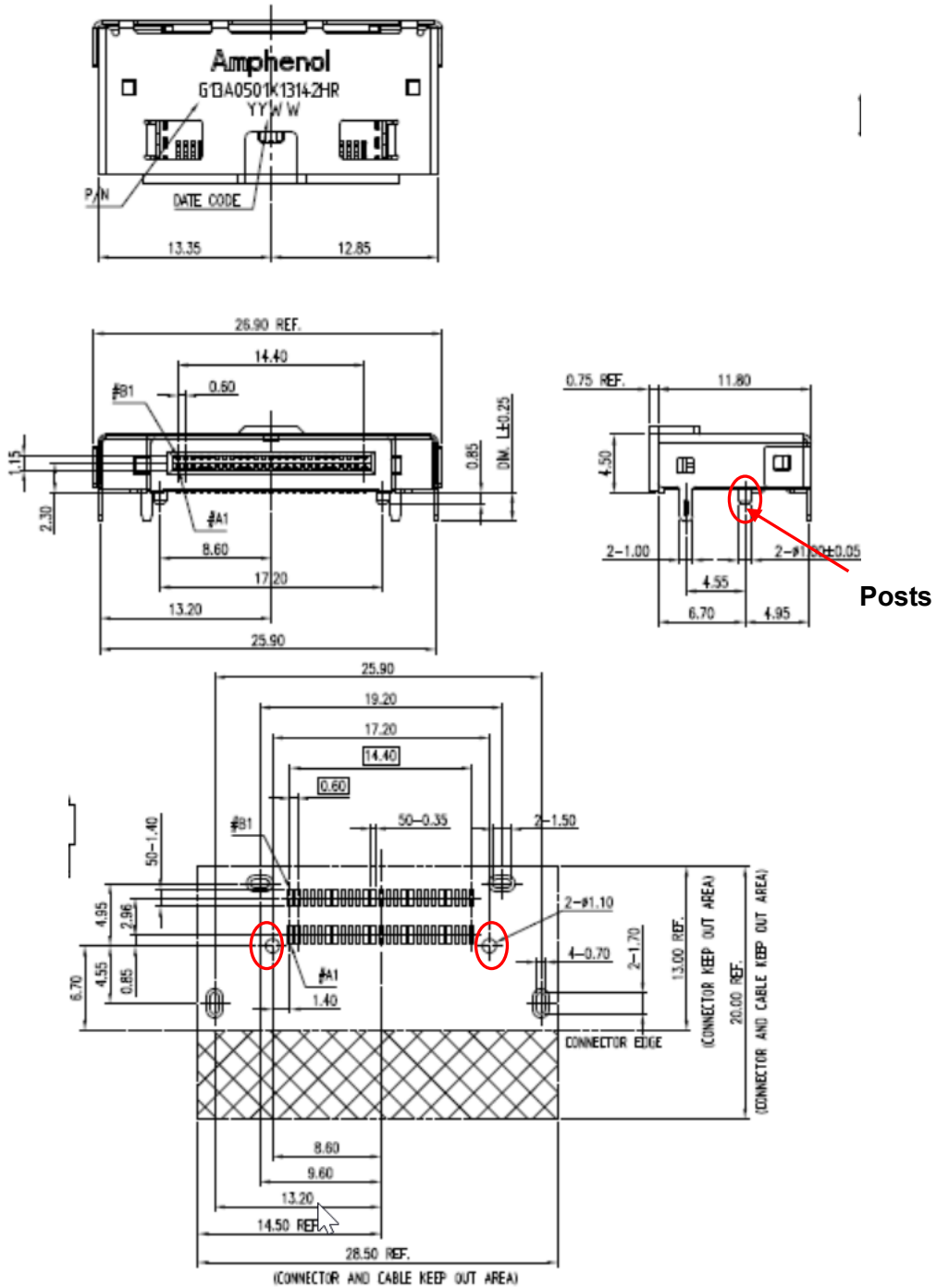


RECOMMENDED PCB LAYOUT- TOP VIEW
(GENERAL TOLERANCE: ±0.05)

Flash 1.0

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RECOMMENDED PCB LAYOUT- TOP VIEW
(GENERAL TOLERANCE: ±0.05)

Flash 2.0
Figure 2

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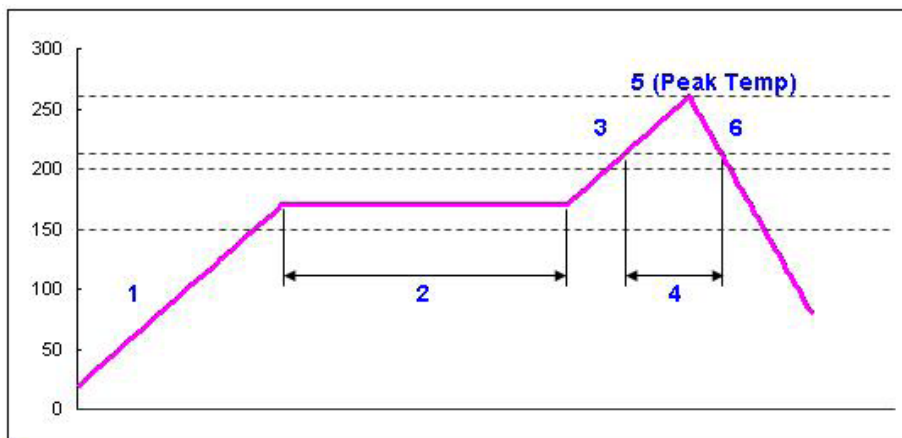
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4.2 IR Reflow Profile

The aperture of the stencil is dependence on the circuit pad size and stencil thickness. For SMT tail commended the stencil thickness should not be less than 0.13 mm, but don't include shell DIP tail. The stencil aperture size of at least 90% of pad size should be used. When a thinner stencil is used, the apertures may have to be enlarged slightly to facilitate sufficient paste, in order to ensure a good joint.

The PCB containing the connector should be reflowed using a reflow profile which is in compliance with the customer's data sheet for the paste used or as per product specification for the series. For recommended reflow profile, please refer to respective product specification. (see Figure 3)

It is recommended that the soak time be long enough to allow temperature to stabilize over the whole area under the connector and the time above liquid be long enough for total reflow. This component is suitable for processing through the temperatures used in lead free processes but should not be subjected to temperatures in excess of 260°C



1	Average ramp rate	3°C per second max.
2	Pre-heat temp.(minimum)	150°C
	Pre-heat temp.(maximum)	200°C
	Pre-heat time	60 to 120 seconds
3	Ramp to peak	3°C per second max.
4	Time over liquidus(217°C)	60 to 150 seconds
5	Peak temp.	260 +0/-10°C
	Time within 5°C of peak	10 seconds max.
6	Ramp- cool down	6°C per second max.
	Time 25°C to peak	8 minutes max.

Figure 3

Note: Recommended the nozzle put the RA connector on PCB to press over 0.1mm in SMT process

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4.3 Rework and Repair

It is recommended that a commercially available hot air rework station be used for the repair of this product. Many of these repair stations are readily available and the selected manufacturer is based on a matter of choice. It is very important that the correct nozzle be used for this operation.

Dependent on the card thickness and stack up, in some circumstances, it may be desirable to pre-heat in an oven to 100°C gradually and hold for 30 to 60 minutes to avoid thermal shock to the PCB. It is recommended to shield adjacent components especially component body and solder joints during the rework process to avoid overheating and melting of the joints.

For removal process, this connector should be removed manually. To avoid additional heat cycle, excessive solder should be removed from the site immediately after the connector lifted off, while the board is still hot. A hand held, solder vacuum tool or solder wicking braid can be used. Both methods should be performed by qualified operators only. This is because damage to the board or pads is the greatest concern. After the removal, this connector should now be discarded as it cannot be reused.

Before replacing with a new connector, the residual solder on the pads should be removed using either a vacuum scavenging system or by hand from a skilled operator. Then the solder pads should be cleaned with alcohol and brush to ensure a clean surface. It is recommended that the pads be pasted again using a 0.13mm stencil. Once the new connector has been placed on the PCB, it should be reflowed.

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5. 0 MATING and UNMATING of Receptacle and Plug

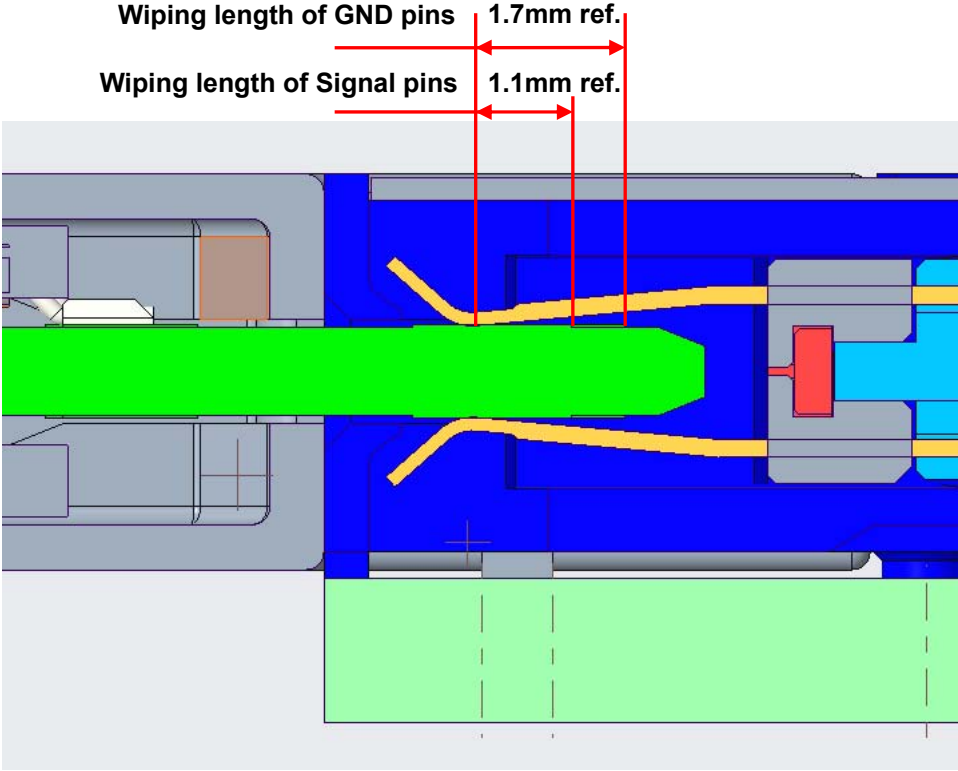


Figure 4

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